

REMARKSAmendments

In the descriptive part of the specification, the status of this application as a continuation-in-part has been added, and various minor errors have been corrected.

In the claims, claims 1 to 17 have been cancelled.

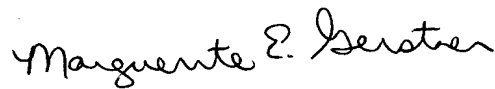
In the drawings, Figure 6 has been amended. As filed, Figure 6 incorrectly identified two elements on the lower right side of composite device 2 as element "12". It is apparent from reviewing the specification (page 20, lines 19 to 20) and the lower left corner of composite device 2 that the lower occurrence of "12" should be --9-- for insulating substrate 9. This proposed change is marked in red on the attached sheet 3/9.

Attached hereto is a marked-up version of changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made".

Conclusion

It is believed that this application is now in condition for allowance and such action at an early date is earnestly requested. If, however, there are any outstanding issues which can be usefully discussed by telephone, the Examiner is asked to call the undersigned.

Respectfully submitted,



Marguerite E. Gerstner
Registration No. 32,695
Telephone (650) 361-2483

VERSION WITH MARKINGS TO SHOW CHANGES MADEIn the Specification

The following two paragraphs have been added before the heading beginning at page 1, line 3 of the specification (i.e. the heading "Background of the Invention"):

--Reference to Related Applications

This application is the national stage of International Application No. PCT/US00/25118, filed September 13, 2000, which is a continuation-in-part of U.S. Application No. 09/395,869, filed September 14, 1999. The disclosure of each of these applications is incorporated herein by reference.--

The paragraph beginning at page 20, line 19 of the specification has been amended as follows:

Figure 6 shows in cross-section a composite device 2 as in Figure 5 soldered to traces 41 and 43 on an [in] insulating substrate 9.

The paragraph beginning at page 22, line 8 of the specification has been amended as follows:

Figure 21 illustrates a composite device which has only one internal electrode 16, formed from a stack with only one internal conductive surface. A laminar element 17 is combined with the laminar element 76 [78]. The laminar elements can be pressed together to form a bond, so that no third laminar element is required to secure the laminar elements together. For example, 17 can comprise a PTC element and 76 [78] can comprise a dielectric substrate with adhesive properties.

The paragraph beginning at page 24, line 6 of the specification has been amended as follows:

One surface of one foil layer of each of two laminates was [were] patterned using an etching technique in which the surface was [they were] first coated with an etch resist, then imaged in a desired pattern. The etch resist was developed and etching was accomplished using cupric chloride before the resist was stripped away. These same foil layers were patterned to define the periphery of the individual devices and the residual conductive members. In addition, the outer edges of the metal foil on the laminate were etched to

provide an alternating cross directional pattern around the perimeter, as shown in Figure 2. Paths providing electrical continuity were utilized during the subsequent electrolytic plating of Sn/Pb.

The two paragraphs beginning at page 26, line 11 of the specification have been amended as follows:

A stacked assembly in accordance with Figure 26 was prepared by the following method. One laminate having a thickness of about 0.198 mm (0.0078 inch) was prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both major sides of a 0.127 mm (0.005 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 37% by volume carbon black (Raven™ 430) with about 10.5% by volume high density polyethylene (LB832, manufactured by Equistar) and about 52.5% copolymer (EBA705, manufactured by Equistar), as in Example 1, [1.] and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.10 m x 0.41 m (4 inch x 16 inch).

The laminate was drilled with registration holes as in Example 1 and with holes having a diameter of 1.27 [0.127] mm (0.050 inch) to create apertures in the laminate. Four layers of 0.038 mm (0.0015 inch)-thick layer of epoxy pre-preg (44N Multifilm, available from Arlon) and two layers of 1 oz Cu foil treated as in Example 2 [1] were also drilled with registration holes suitable for alignment.

In the Claims

Claims 1 to 17 have been canceled.

In the Drawings

Figure 6 has been replaced by replacement Figure 6.